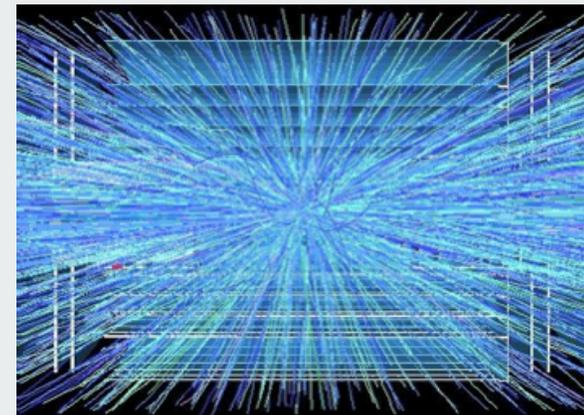
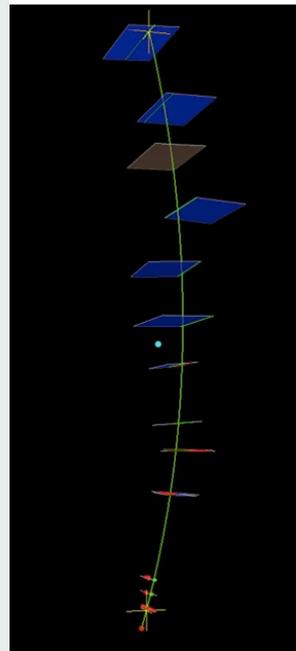
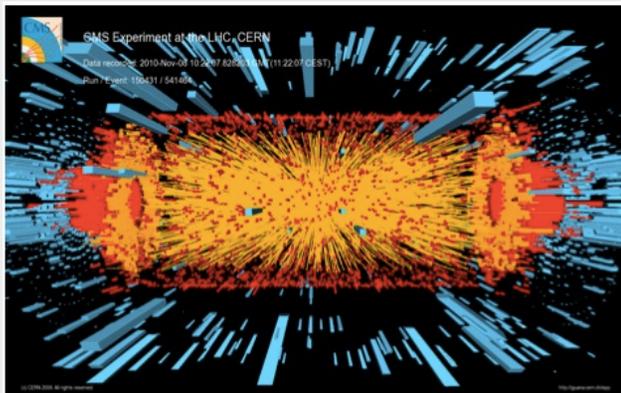




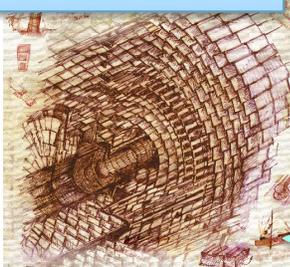
# Possible future direction for Precision Position and Timing detector R&D using 3DIC technology - Ted Liu (FNAL)

July 30, 2020

Snowmass IF07 Electronics ASIC  
Flashrtalks workshop



Detector design for triggering



Data reduction using "stub finding"

Data transfer

Data formatting

Tracking Trigger challenges at HL-LHC

Partition detector into trigger towers/sectors

Pick your favorite method:  
Associative Memory Approach  
Hough Transformation  
Adaptive Pattern Recognition  
Biology Inspired ...  
your choice here...

Pattern Recognition

Finer pattern recognition

Track Fitting

- Challenging issues

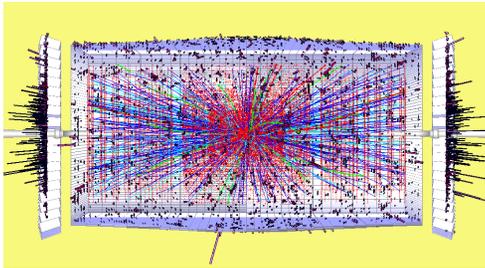
- (1) Data Reduction at detector/sensor stage
- (2) Data Transfer (rad hard, high bandwidth, low power link)
- (3) Data Formatting
- (4) Pattern Recognition
- (5) Track Fitting ...

Will only use HL-LHC tracking trigger as an example here:

**The need for precision timing and position detector in the future (beyond HL-LHC)**

(there are many other motivations for precision timing & position detector)

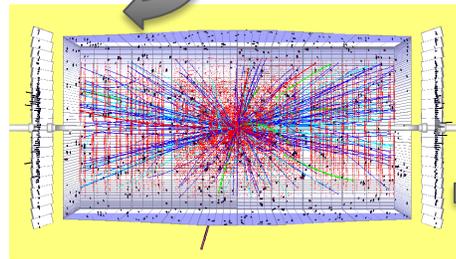
Ted Liu, Precision Position & Timing



Raw info produced by CMS tracker at HL-LHC

Bandwidth required:  
~ 100 Tbps

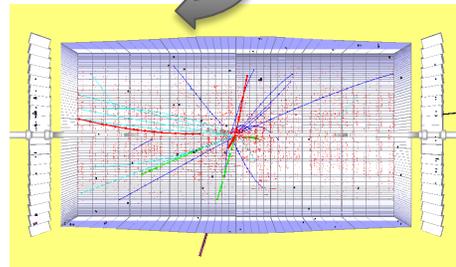
**“Stub finding” is a crucial step to reduce the raw data volume ...**



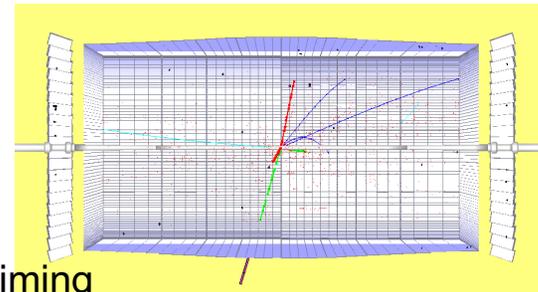
After **stub finding** at module level  
(~ 10 -20 reduction)

**After Pattern Recognition**  
(~ 10 reduction)

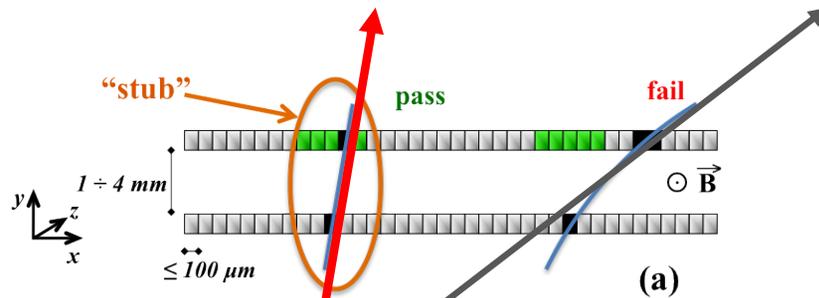
One way to **imagine**  
different stages of processing  
(just conceptually)



After **Track Fitting**  
and later  
event vertexing

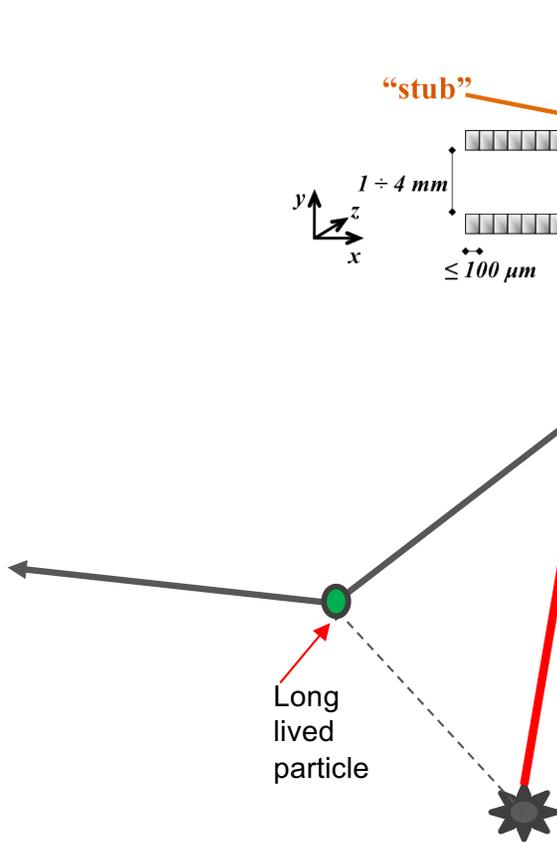


# Essence of stub finding: the short coming



(a)  
The stub finding assumes the track is originated from IP (interaction point), and it prefers the high Pt tracks while rejecting slow moving tracks (curved)

*a track from a long lived particle (due to new physics) decay would fail the selection*





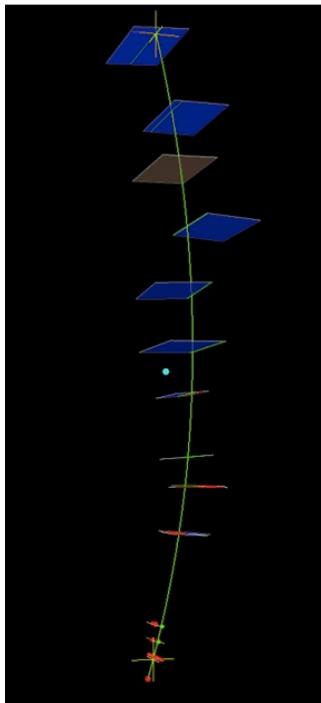
# Pattern recognition and track fitting stage

Low luminosity case

vs.

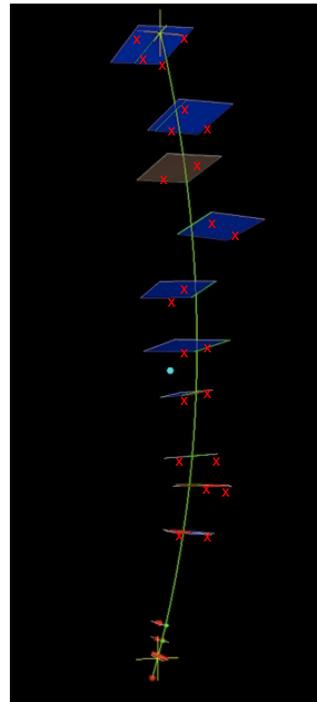
High luminosity case

high luminosity case with timing



In the high luminosity case,  
many random hits will  
still survive pattern  
recognition stage

Track fitting stage has  
to try out all combinations

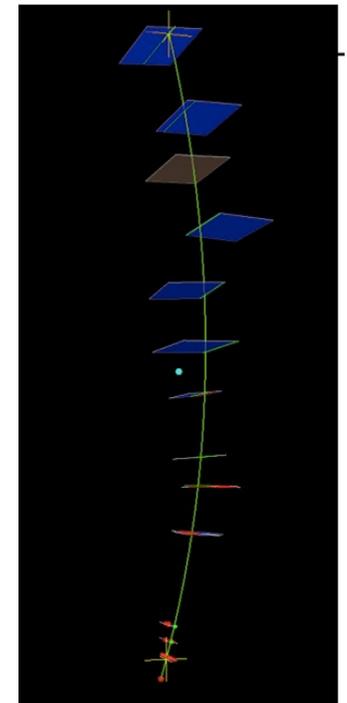


*If precision timing  
information is available,  
and used in the pattern  
recognition stage,  
most of the random hits  
could be removed ....*

*(for beyond HL-LHC)*



*Food for thought*



Detector design for triggering



## Trigger @ future hadron collider(s) → the view from HL-LHC (or a wild guess)

Data transfer (rad hard) high bandwidth low power data link

Data formatting

There are new challenges:

- (0) *tracker with precision timing & position*
- (1) *Data Reduction at detector/sensor stage with precision timing & position info*
- (2) *Data Transfer (rad hard, high bandwidth, low power link)*
- (3) *Data Formatting (with precision timing info)*
- (4) *Pattern Recognition (with precision timing info)*
- (5) *Track Fitting (with precision timing info)*

Pattern Recognition

Track Fitting

Machine learning ...

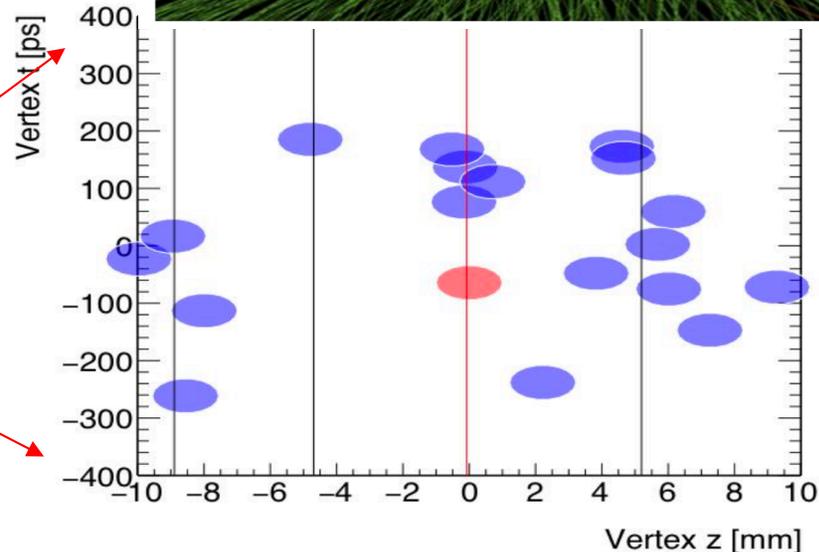
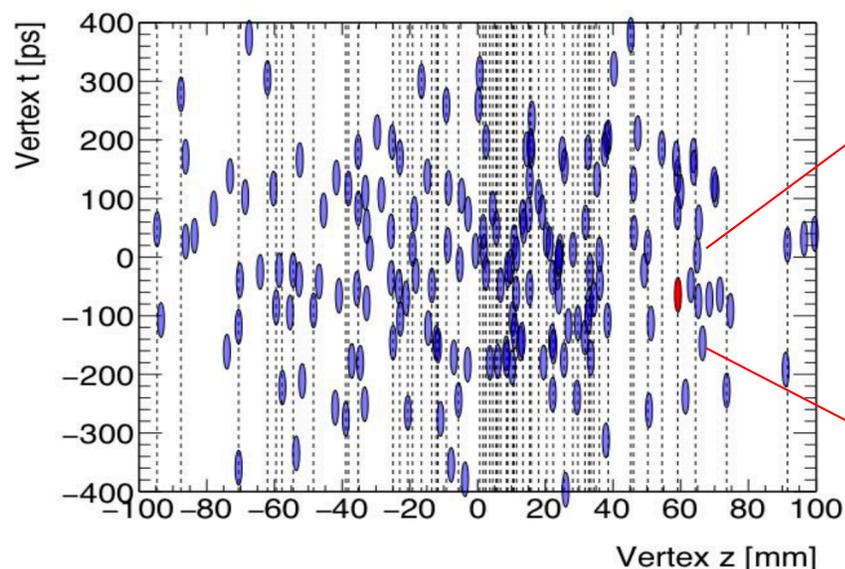
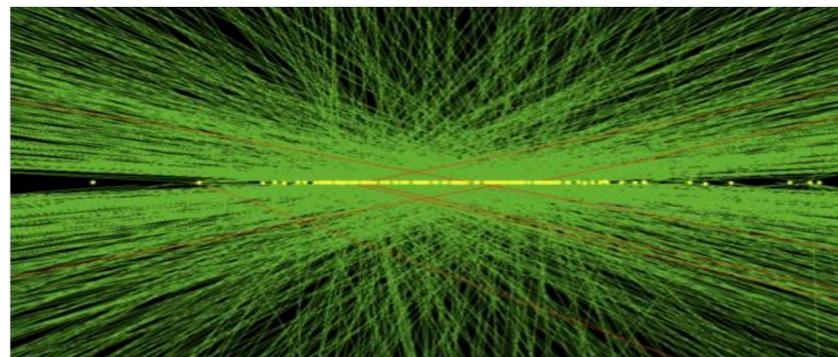
Modern FPGAs

Open question: *what if fast timing be used in tracking trigger?  
(pattern recognition and tracking in 4D: both space and time)  
what is the highest luminosity one could handle? (beyond 1E35?)*

HLT

# Precision timing detectors for HL-LHC

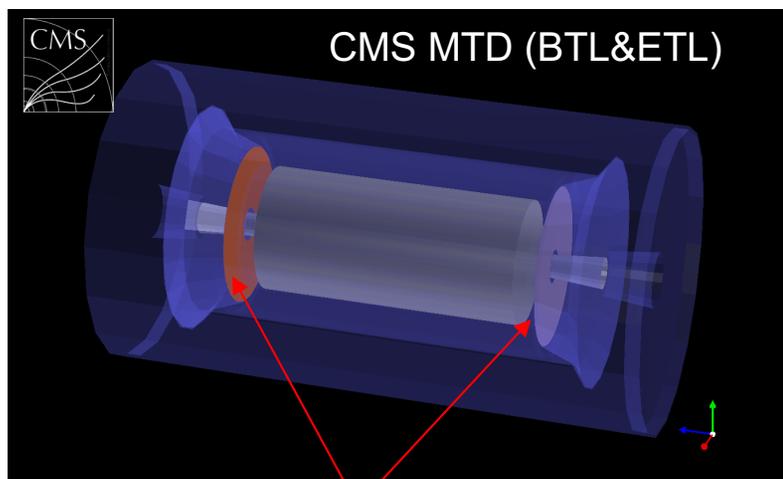
## *Precision timing & event vertex association*



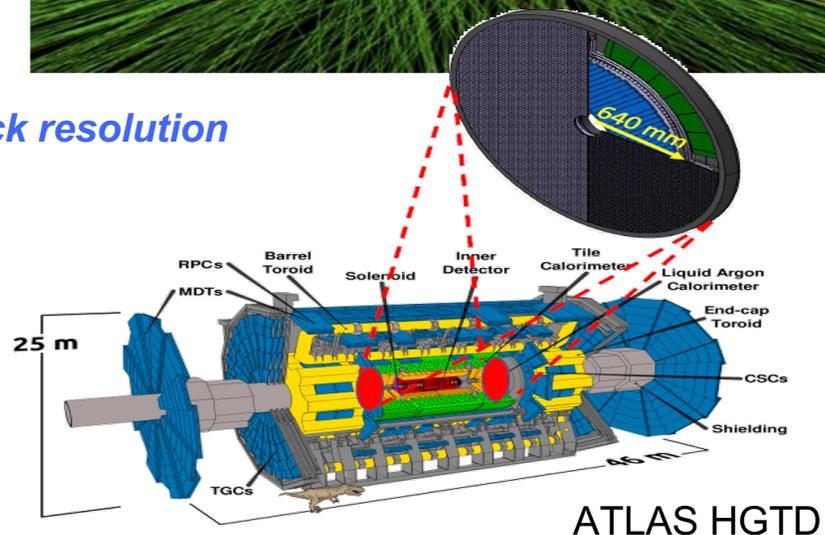
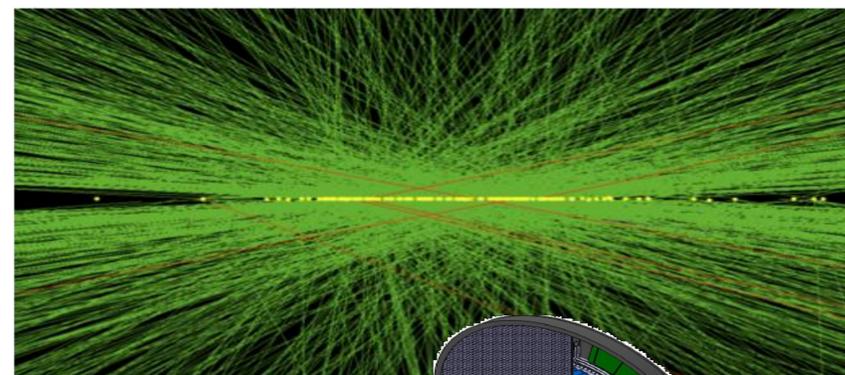
Event display showing the time and z position of all vertices in an event with 200 additional interactions. Blue ellipses correspond to truth vertices. The size of the ellipses are 30ps and 1mm. The red ellipse indicates the truth hard-scatter vertex. The dotted lines indicate the position of the reconstructed primary vertices. The right plot is a zoom around the hard-scatter vertex.

# Precision timing detectors for HL-LHC

What we have learned and challenges ahead of us to develop precision timing & position detectors for beyond HL-LHC ...



~ 30 ps per track resolution



Will use CMS ETL (Endcap) as an example: ETROC chip

The LGAD sensor (2cm x 4cm) has a pixel size of 1.3 mm x 1.3mm (quite large)

For LGAD sensor for precision timing applications, see Abe Seiden's talk today:

<https://indico.fnal.gov/event/44596/>

# ETROC (CMS ETL ReadOut Chip) in 65nm

The 16x16 pixel array ETROC is bump-bonded to 16x16 sensor pixel array of LGAD

The size of pixel: 1.3 mm x 1.3mm (the same size for ATLAS HGTD)

LGAD size: ~ 2cm x 4cm  
ETROC size: ~2cmx2cm

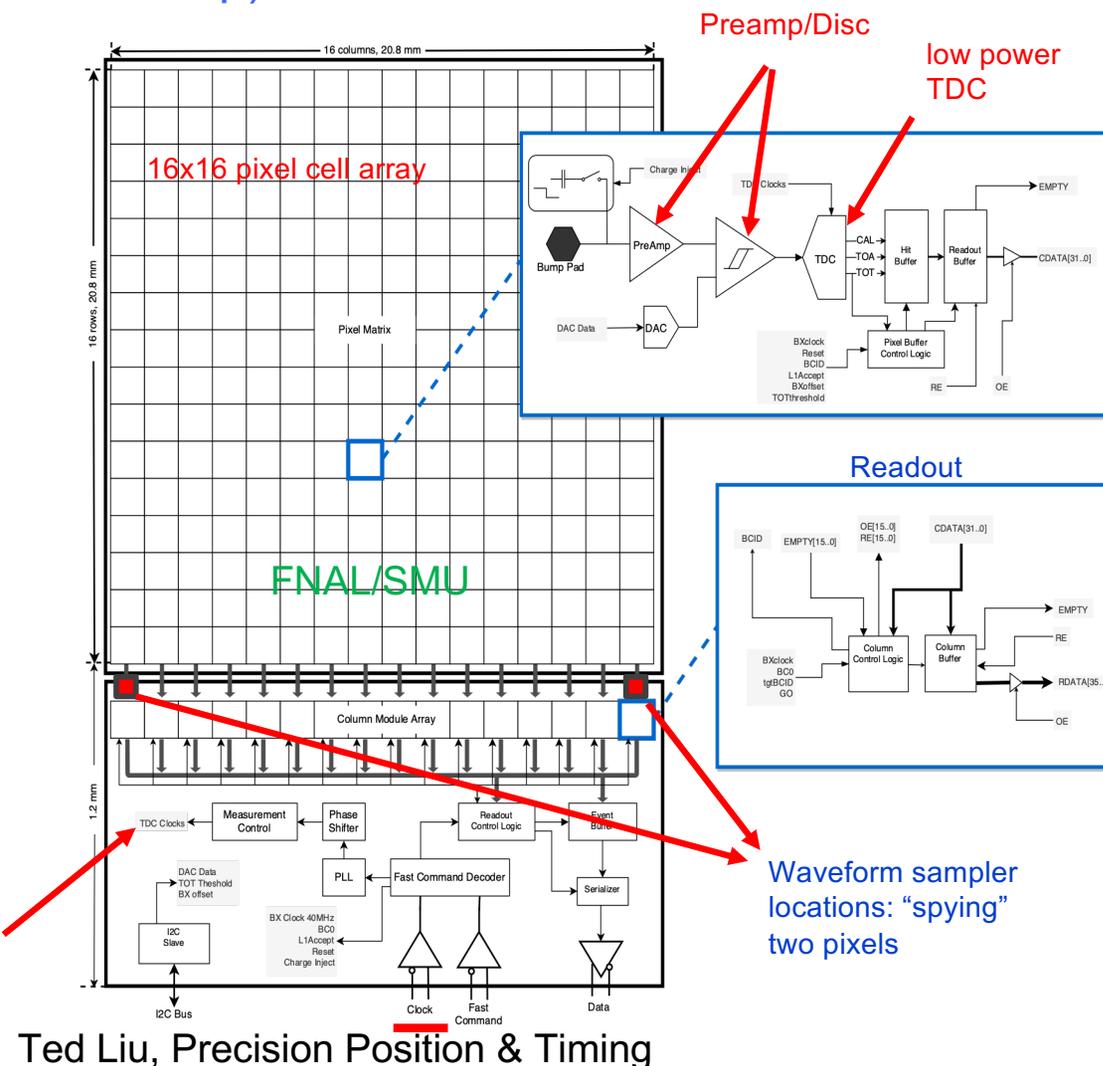
*This is the first generation precision timing detector (~30 ps level)... but by no means precision position detector.*

*To also have precision position information, the pixel size needs to be scaled from 1.3mm x 1.3mm down to about ~ 100 um x 100 um level or so ...*

*(a factor of ~170)*

*This is challenging!*

Precision clock distribution to all pixels



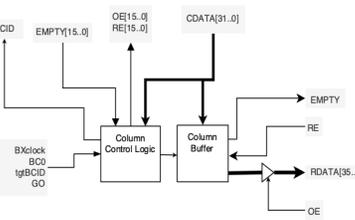
Preamp/Disc

low power TDC

16x16 pixel cell array

FNAL/SMU

Readout

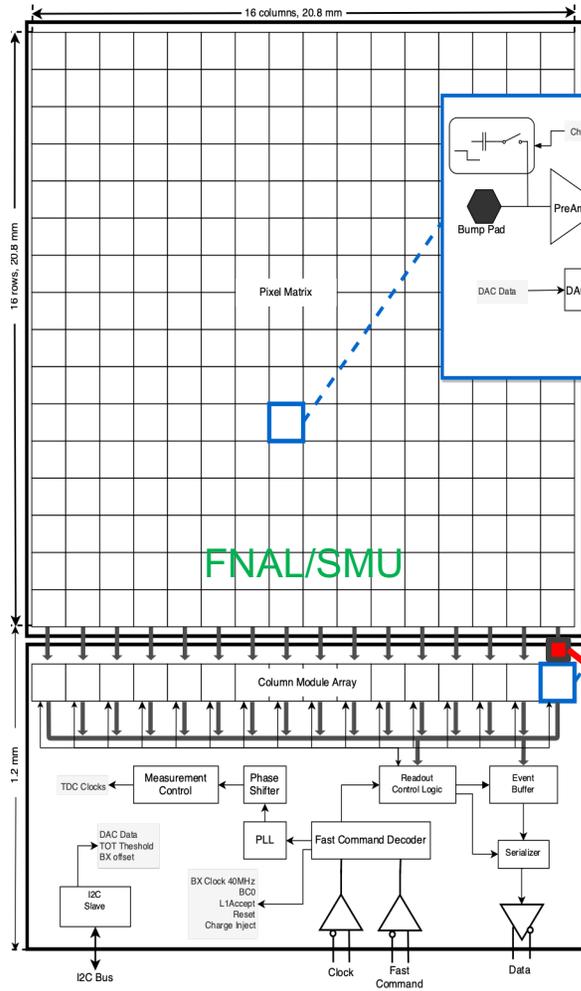


Waveform sampler locations: "spying" two pixels

# What we have learned from ETROC (CMS ETL ASIC)

65nm implementation

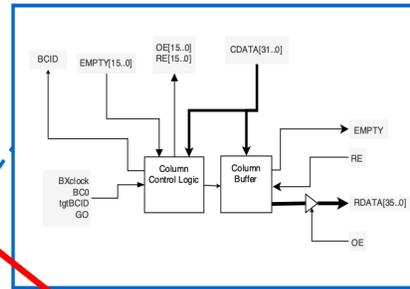
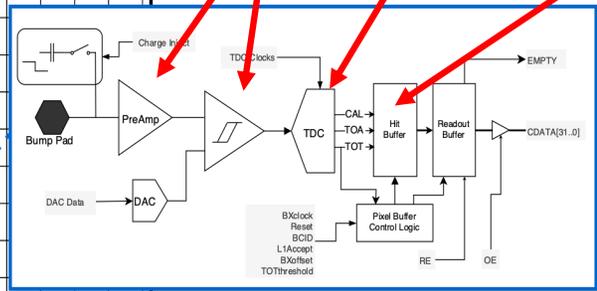
16x16 pixel cell array (1.3mm x 1.3 mm)



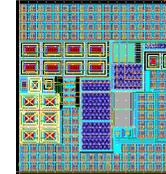
Preamp/Disc

low power TDC

Hit buffer

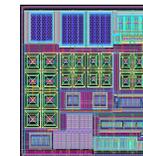


90 um X 94 um



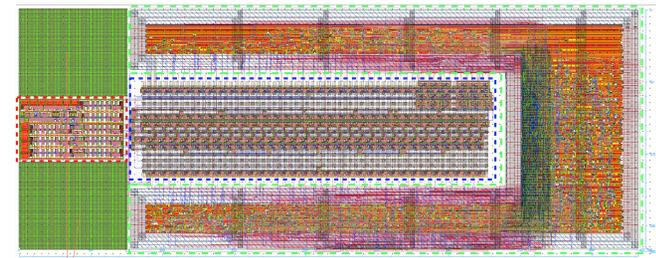
Preamp

81 um X 67 um



Discriminator

467 um X 166 um (can be subdivided)



TDC

Decoupling Capacitors

Red dashed line part: TDC Controller  
Blue dashed line part: TDC Delay Line  
Green dashed line part: TDC Encoder

300um x 800um

3.2GS/s waveform sampler

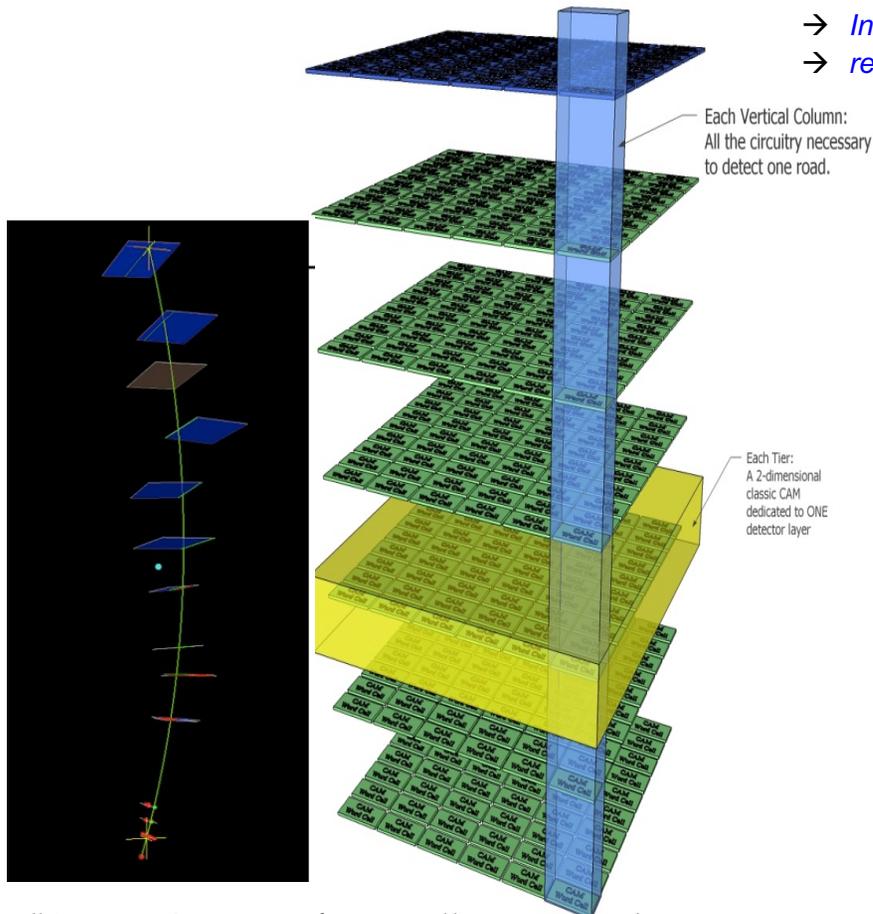
Ted L. Precision Position & Timing

SRAM hit buffer  
250 um x 150 um

(can be subdivided)

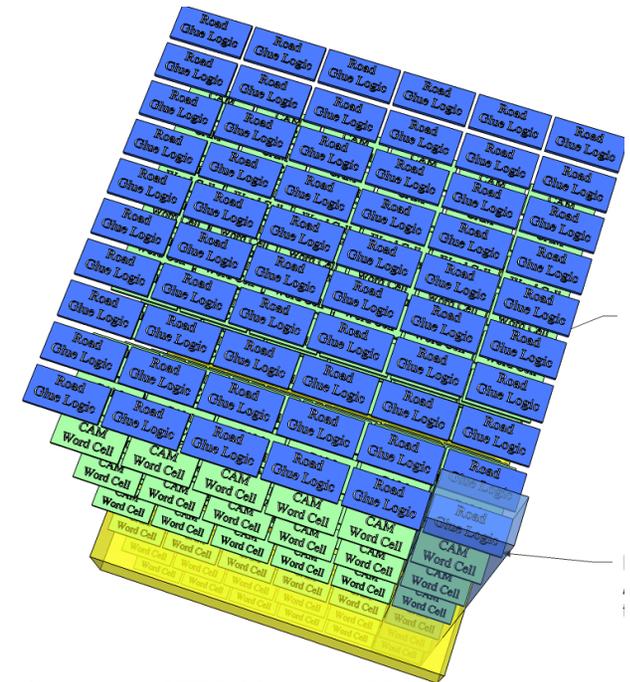
Hit circular buffer

## 3DIC Technology



The 3DIC stack can be very thin ( $< \sim 10 \mu\text{m}$  per tier)

- *Interconnection much better than bump-bonding*
- *reduced power density or increased speed*



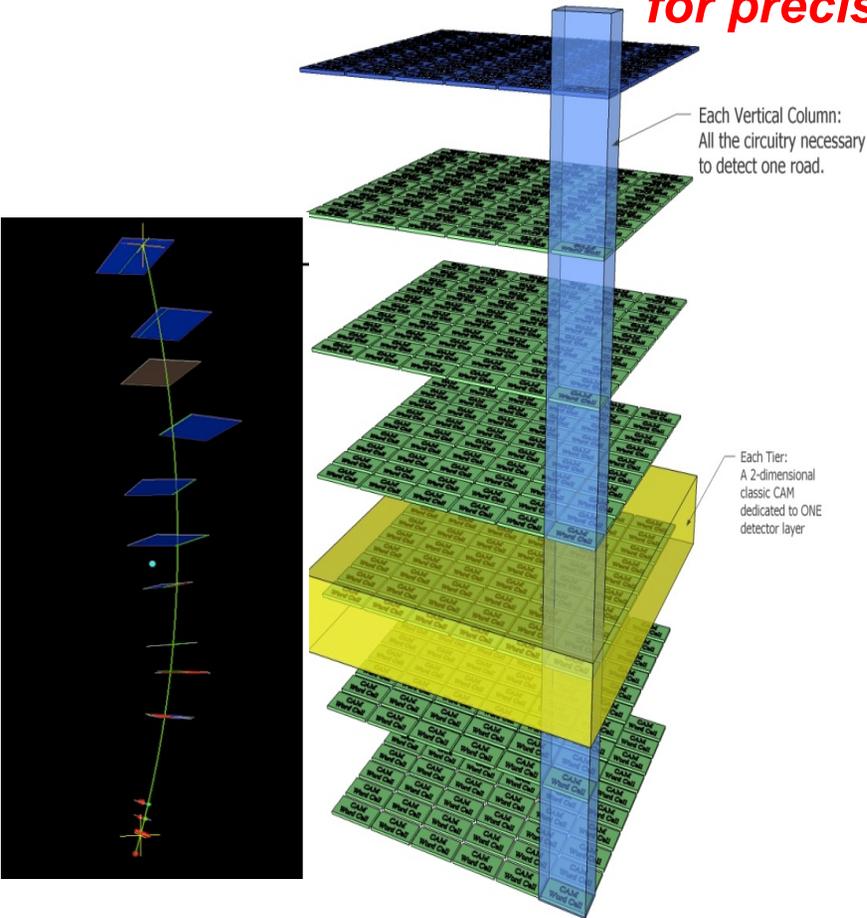
- In 3D, with 130 nm, VIRPAM  $\sim 160\text{K}$  AM patterns/cm<sup>2</sup>
- CDF AMchip03: 180 nm, standard cell, 5K AM patterns/chip

“A New Concept of Vertically Integrated Pattern Recognition Associative Memory”  
TIPP 2011 Proceedings <http://www.sciencedirect.com/science/article/pii/S1875389212019165>

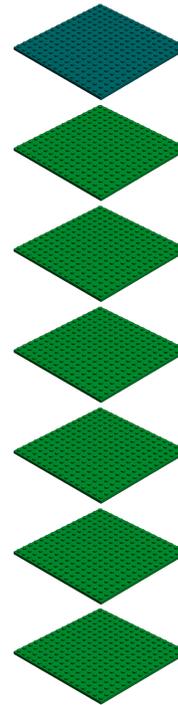
Ted Liu, Precision Position & Timing

3DIC Technology

## How could 3DIC help to scale to smaller pixel size for precision position & timing detectors



*An open flexible architecture for precision position and timing detector (one example below)*



- Readout and interfaces
- Hit buffer
- Clock distribution
- TDC
- Discriminator
- preamp stage
- Sensor pixels (~100 um x ~ 100um each)

*3DIC allows repartition of the design blocks vertically for the whole processing chain... also combination of different technology, Or even sensors ...*

## Outlook:

### Precision Position & Timing detector & Future Hadron Colliders

- Generally speaking, the ultimate physics reach of any higher energy hadron collider (given a center-of-mass energy) will be governed by its luminosity.
- Given the huge cost associated with any future higher energy hadron collider, *it is crucial to push for higher luminosity* (similar to HL-LHC). This is to maximize the new physics reach of the huge investment already made, before a new higher energy collider can be proposed or built.
- *Because precision position & timing information is the most effective means for triggering and high pile-up mitigation, high precision position and timing tracking detector will be mandatory for any future hadron colliders*
- *3DIC technology allows an open flexible architecture for future precision position and timing detector development (within and beyond HEP)*

*The existing new precision timing detector projects (such as CMS MTD, ATLAS HGTD): not only will they be important for the success of physics program in the HL-LHC era, they also lay some of the technological foundations for the future of the field...*